

PRODUCT DATA SHEET Thermal Grizzly Conductonaut

Description:

Thermal Grizzly Conductonaut is a high performance liquid metal themal compound.

Properties:

Thermal Grizzly Conductonaut liquid metal thermal compound is based on a eutectic alloy. A special combination of metals like tin, gallium and indium results in very high thermal conductivity and excellent long-term stability.

Application:

Thermal Grizzly Conductonaut is recommended for applications that require extremely high thermal conductivity at room temperature – e.g. between a silicon chip PC microprocessor and heat sink. The liquid metal compound compensates even the

slightest irregularities, which can not be achieved with convenstional thermal greases.

Storage:

Thermal Grizzly Conductonaut should be stored boxed and under dry conditions at room temperature.



Property	Value/Description	Property	Value/Description
Density	6,24g/cm³	Standard sizes	1g
Application temperature	10° C bis 140° C	Possible thickness	variable
Thermal conductivity	73 W/mk	Silicone based	no
Consistency	liquid	Typical Application	CPUs, GPUs,
Color	silver		Notebooks, ICs

^{*}following DIN 51412-1

All of these data were determined and confirmed with the technical facilities of http://overclocking.guide.

Trademark Information:

Thermal Grizzly is a registered trademark.

Please note:

The data in this technical data sheet are based on our current knowledge and experience. Due to the large amount of possible factors, this should not be construed as to release the users from doing their own tests and screening. No legally binding assurance

of specific properties or applicability for a concrete purpose should be derived from these data. Please consider contacting us for further detail.

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